

Octal 3-State Non-Inverting D Flip-Flop High-Performance Silicon-Gate CMOS

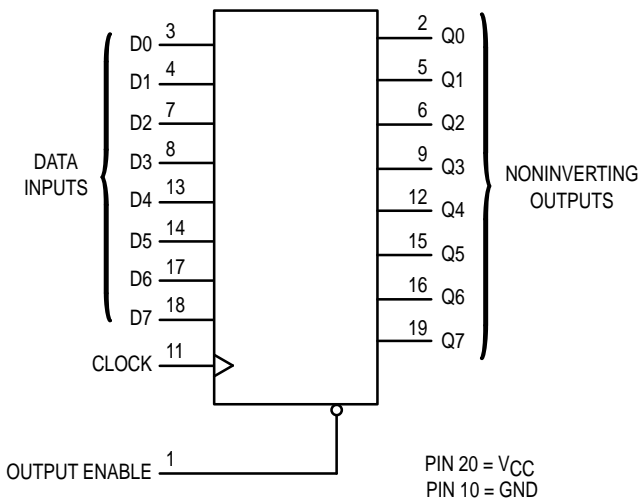
The MC54/74HC374A is identical in pinout to the LS374. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

Data meeting the setup time is clocked to the outputs with the rising edge of the clock. The Output Enable input does not affect the states of the flip-flops, but when Output Enable is high, the outputs are forced to the high-impedance state; thus, data may be stored even when the outputs are not enabled.

The HC374A is identical in function to the HC574A which has the input pins on the opposite side of the package from the output. This device is similar in function to the HC534A which has inverting outputs.

- Output Drive Capability: 15 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1.0 μ A
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements Defined by JEDEC Standard No. 7A
- Chip Complexity: 266 FETs or 66.5 Equivalent Gates

LOGIC DIAGRAM

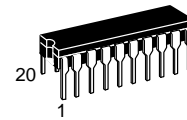


FUNCTION TABLE

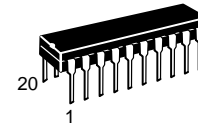
| Inputs | | Output | |
|---------------|-------|--------|-----------|
| Output Enable | Clock | D | Q |
| L | | H | H |
| L | | L | L |
| L | L, H, | X | No Change |
| H | X | X | Z |

X = don't care
Z = high impedance

MC54/74HC374A



J SUFFIX
CERAMIC PACKAGE
CASE 732-03



N SUFFIX
PLASTIC PACKAGE
CASE 738-03



DW SUFFIX
SOIC PACKAGE
CASE 751D-04



SD SUFFIX
SSOP PACKAGE
CASE 940C-03

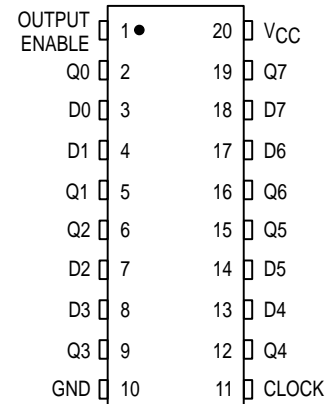


DT SUFFIX
TSSOP PACKAGE
CASE 948E-02

ORDERING INFORMATION

| | |
|--------------|---------|
| MC54HCXXXAJ | Ceramic |
| MC74HCXXXAN | Plastic |
| MC74HCXXXADW | SOIC |
| MC74HCXXXASD | SSOP |
| MC74HCXXXADT | TSSOP |

PIN ASSIGNMENT



MAXIMUM RATINGS*

| Symbol | Parameter | Value | Unit |
|------------------|----------------------------------------------------------------------------------------------------------------|--------------------------------|------|
| V _{CC} | DC Supply Voltage (Referenced to GND) | - 0.5 to + 7.0 | V |
| V _{in} | DC Input Voltage (Referenced to GND) | - 0.5 to V _{CC} + 0.5 | V |
| V _{out} | DC Output Voltage (Referenced to GND) | - 0.5 to V _{CC} + 0.5 | V |
| I _{in} | DC Input Current, per Pin | ± 20 | mA |
| I _{out} | DC Output Current, per Pin | ± 35 | mA |
| I _{CC} | DC Supply Current, V _{CC} and GND Pins | ± 75 | mA |
| P _D | Power Dissipation in Still Air, Plastic or Ceramic DIP† SOIC Package† SSOP or TSSOP Package† | 750 500 450 | mW |
| T _{stg} | Storage Temperature | - 65 to + 150 | °C |
| T _L | Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP, SOIC, SSOP or TSSOP Package) (Ceramic DIP) | 260 300 | °C |

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range GND ≤ (V_{in} or V_{out}) ≤ V_{CC}. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

* Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

† Derating — Plastic DIP: - 10 mW/°C from 65° to 125°C
Ceramic DIP: - 10 mW/°C from 100° to 125°C
SOIC Package: - 7 mW/°C from 65° to 125°C
SSOP or TSSOP Package: - 6.1 mW/°C from 65° to 125°C

For high frequency or heavy load considerations, see Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

RECOMMENDED OPERATING CONDITIONS

| Symbol | Parameter | Min | Max | Unit | |
|------------------------------------|------------------------------------------------------|-------------------------------------------------------------------------------|-----------------|--------------------|----|
| V _{CC} | DC Supply Voltage (Referenced to GND) | 2.0 | 6.0 | V | |
| V _{in} , V _{out} | DC Input Voltage, Output Voltage (Referenced to GND) | 0 | V _{CC} | V | |
| T _A | Operating Temperature, All Package Types | - 55 | + 125 | °C | |
| t _r , t _f | Input Rise and Fall Time (Figure 1) | V _{CC} = 2.0 V V _{CC} = 4.5 V V _{CC} = 6.0 V | 0 0 0 | 1000 500 400 | ns |

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

| Symbol | Parameter | Test Conditions | V _{CC} V | Guaranteed Limit | | | Unit |
|-----------------|-----------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------|----------------------|------------------|--------|---------|------|
| | | | | - 55 to 25°C | ≤ 85°C | ≤ 125°C | |
| V _{IH} | Minimum High-Level Input Voltage | V _{out} = 0.1 V or V _{CC} - 0.1 V I _{out} ≤ 20 μA | 2.0 | 1.50 | 1.50 | 1.50 | V |
| | | | 3.0 | 2.10 | 2.10 | 2.10 | |
| | | | 4.5 | 3.15 | 3.15 | 3.15 | |
| | | | 6.0 | 4.20 | 4.20 | 4.20 | |
| V _{IL} | Maximum Low-Level Input Voltage | V _{out} = 0.1 V or V _{CC} - 0.1 V I _{out} ≤ 20 μA | 2.0 | 0.50 | 0.50 | 0.50 | V |
| | | | 3.0 | 0.90 | 0.90 | 0.90 | |
| | | | 4.5 | 1.35 | 1.35 | 1.35 | |
| | | | 6.0 | 1.80 | 1.80 | 1.80 | |
| V _{OH} | Minimum High-Level Output Voltage | V _{in} = V _{IH} or V _{IL} I _{out} ≤ 20 μA | 2.0 | 1.90 | 1.90 | 1.90 | V |
| | | | 4.5 | 4.40 | 4.40 | 4.40 | |
| | | | 6.0 | 5.90 | 5.90 | 5.90 | |
| | | V _{in} = V _{IH} or V _{IL} I _{out} ≤ 2.4 mA I _{out} ≤ 6.0 mA I _{out} ≤ 7.8 mA | 3.0 | 2.48 | 2.34 | 2.20 | V |
| | | | 4.5 | 2.98 | 3.84 | 3.70 | |
| | | | 6.0 | 5.48 | 5.34 | 5.20 | |

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

| Symbol | Parameter | Test Conditions | V _{CC} V | Guaranteed Limit | | | Unit |
|-----------------|------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------|----------------------|------------------|--------|---------|------|
| | | | | - 55 to 25°C | ≤ 85°C | ≤ 125°C | |
| V _{OL} | Maximum Low-Level Output Voltage | V _{in} = V _{IH} or V _{IL} I _{out} ≤ 20 μA | 2.0 | 0.10 | 0.10 | 0.10 | V |
| | | | 4.5 | 0.10 | 0.10 | 0.10 | |
| | | | 6.0 | 0.10 | 0.10 | 0.10 | |
| | | V _{in} = V _{IH} or V _{IL} I _{out} ≤ 2.4 mA I _{out} ≤ 6.0 mA I _{out} ≤ 7.8 mA | 3.0 | 0.26 | 0.33 | 0.40 | V |
| | | | 4.5 | 0.26 | 0.33 | 0.40 | |
| | | | 6.0 | 0.26 | 0.33 | 0.40 | |
| I _{in} | Maximum Input Leakage Current | V _{in} = V _{CC} or GND | 6.0 | ± 0.1 | ± 1.0 | ± 1.0 | μA |
| I _{OZ} | Maximum Three-State Leakage Current | Output in High-Impedance State V _{in} = V _{IL} or V _{IH} V _{out} = V _{CC} or GND | 6.0 | ± 0.5 | ± 5.0 | ± 10 | μA |
| I _{CC} | Maximum Quiescent Supply Current (per Package) | V _{in} = V _{CC} or GND I _{out} = 0 μA | 6.0 | 4 | 40 | 160 | μA |

NOTE: Information on typical parametric values can be found in Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

AC ELECTRICAL CHARACTERISTICS (C_L = 50 pF, Input t_r = t_f = 6.0 ns)

| Symbol | Parameter | V _{CC} V | Guaranteed Limit | | | Unit |
|--------------------------------------|----------------------------------------------------------------------------|----------------------|------------------|--------|---------|------|
| | | | - 55 to 25°C | ≤ 85°C | ≤ 125°C | |
| f _{max} | Maximum Clock Frequency (50% Duty Cycle) | 2.0 | 6 | 5 | 4 | MHz |
| | | 3.0 | 15 | 10 | 8 | |
| | | 4.5 | 30 | 24 | 20 | |
| | | 6.0 | 35 | 28 | 24 | |
| t _{PLH} t _{PHL} | Maximum Propagation Delay, Input Clock to Q (Figures 1 and 5) | 2.0 | 125 | 155 | 190 | ns |
| | | 3.0 | 80 | 110 | 130 | |
| | | 4.5 | 25 | 31 | 38 | |
| | | 6.0 | 21 | 26 | 32 | |
| t _{PLZ} t _{PHZ} | Maximum Propagation Delay, Output Enable to Q (Figures 3 and 6) | 2.0 | 150 | 190 | 225 | ns |
| | | 3.0 | 100 | 125 | 150 | |
| | | 4.5 | 30 | 38 | 45 | |
| | | 6.0 | 26 | 33 | 38 | |
| t _{PLZ} t _{PHZ} | Maximum Propagation Delay, Output Enable to Q (Figures 3 and 6) | 2.0 | 150 | 190 | 225 | ns |
| | | 3.0 | 100 | 125 | 150 | |
| | | 4.5 | 30 | 38 | 45 | |
| | | 6.0 | 26 | 33 | 38 | |
| t _{TLH} t _{THL} | Maximum Output Transition Time, Any Output (Figures 1 and 5) | 2.0 | 75 | 95 | 110 | ns |
| | | 3.0 | 27 | 32 | 36 | |
| | | 4.5 | 15 | 19 | 22 | |
| | | 6.0 | 13 | 16 | 19 | |
| C _{in} | Maximum Input Capacitance | | 10 | 10 | 10 | pF |
| C _{out} | Maximum Three-State Output Capacitance (Output in High-Impedance State) | | 15 | 15 | 15 | pF |

NOTE: For propagation delays with loads other than 50 pF, and information on typical parametric values, see Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

| C _{PD} | Power Dissipation Capacitance (Per Enabled Output)* | Typical @ 25°C, V _{CC} = 5.0 V | |
|-----------------|-----------------------------------------------------|-----------------------------------------|----|
| | | | 34 |

* Used to determine the no-load dynamic power consumption: P_D = C_{PD} V_{CC}²f + I_{CC} V_{CC}. For load considerations, see Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

TIMING REQUIREMENTS ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6.0 \text{ ns}$)

| Symbol | Parameter | Fig. | V _{CC} Volts | Guaranteed Limit | | | | | | Unit |
|---------------------------------|-----------------------------------|------|-----------------------|------------------|------|--------|------|---------|------|------|
| | | | | - 55 to 25°C | | ≤ 85°C | | ≤ 125°C | | |
| | | | | Min | Max | Min | Max | Min | Max | |
| t _{su} | Minimum Setup Time, Data to Clock | 3 | 2.0 | 50 | | 65 | | 75 | | ns |
| | | | 3.0 | 40 | | 50 | | 60 | | |
| | | | 4.5 | 10 | | 13 | | 15 | | |
| | | | 6.0 | 9 | | 11 | | 13 | | |
| t _h | Minimum Hold Time, Clock to Data | 3 | 2.0 | 5.0 | | 5.0 | | 5.0 | | ns |
| | | | 3.0 | 5.0 | | 5.0 | | 5.0 | | |
| | | | 4.5 | 5.0 | | 5.0 | | 5.0 | | |
| | | | 6.0 | 5.0 | | 5.0 | | 5.0 | | |
| t _w | Minimum Pulse Width, Clock | 1 | 2.0 | 60 | | 75 | | 90 | | ns |
| | | | 3.0 | 23 | | 27 | | 32 | | |
| | | | 4.5 | 12 | | 15 | | 18 | | |
| | | | 6.0 | 10 | | 13 | | 15 | | |
| t _r , t _f | Maximum Input Rise and Fall Times | 1 | 2.0 | | 1000 | | 1000 | | 1000 | ns |
| | | | 3.0 | | 800 | | 800 | | 800 | |
| | | | 4.5 | | 500 | | 500 | | 500 | |
| | | | 6.0 | | 400 | | 400 | | 400 | |

SWITCHING WAVEFORMS

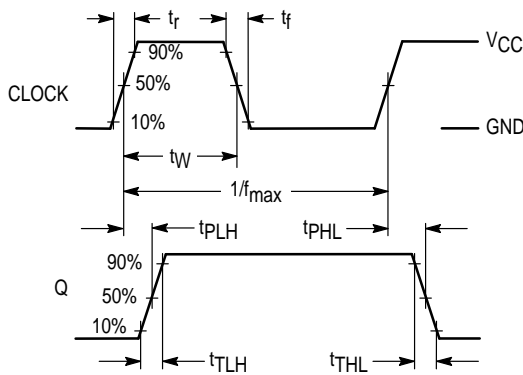


Figure 1.

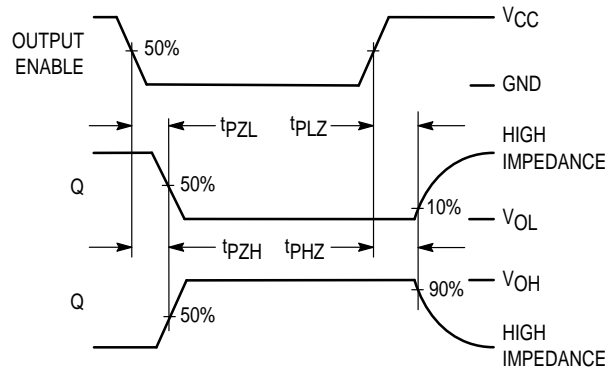


Figure 2.

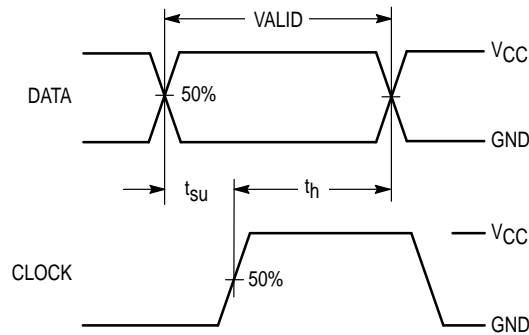
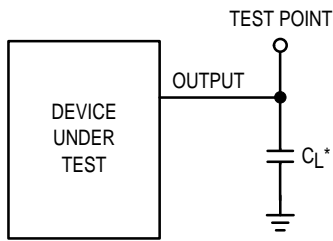


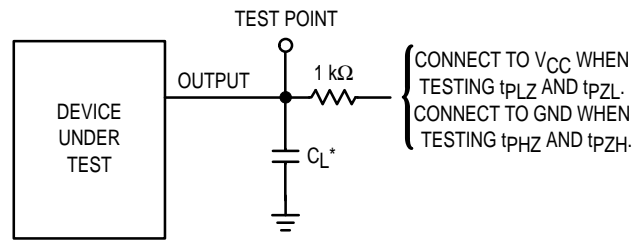
Figure 3.

TEST CIRCUITS



* Includes all probe and jig capacitance

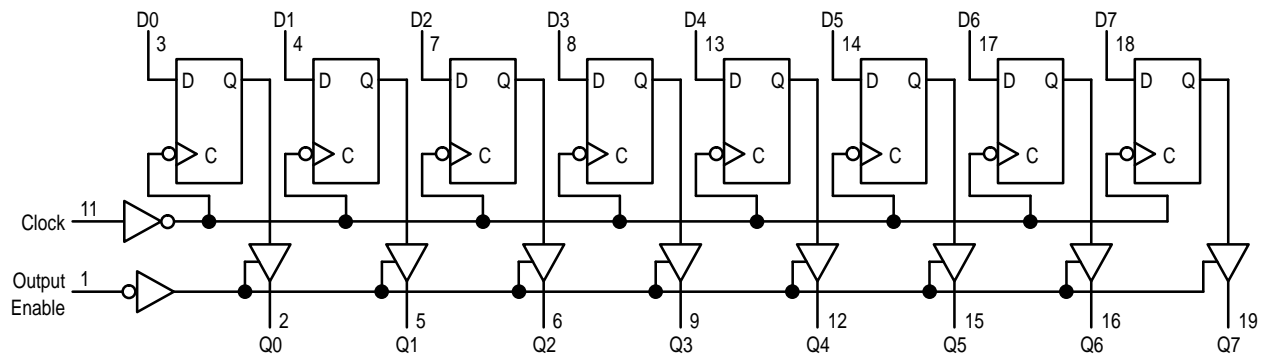
Figure 4.



* Includes all probe and jig capacitance

Figure 5.

EXPANDED LOGIC DIAGRAM



OUTLINE DIMENSIONS

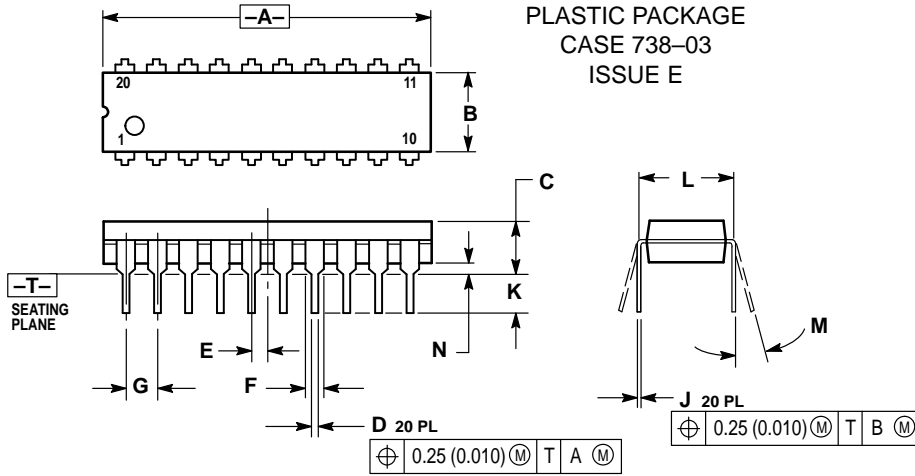
J SUFFIX
CERAMIC PACKAGE
CASE 732-03
ISSUE E



- NOTES:
- LEADS WITHIN 0.25 (0.010) DIAMETER, TRUE POSITION AT SEATING PLANE, AT MAXIMUM MATERIAL CONDITION.
 - DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 - DIMENSIONS A AND B INCLUDE MENISCUS.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|-------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 23.88 | 25.15 | 0.940 | 0.990 |
| B | 6.60 | 7.49 | 0.260 | 0.295 |
| C | 3.81 | 5.08 | 0.150 | 0.200 |
| D | 0.38 | 0.56 | 0.015 | 0.022 |
| F | 1.40 | 1.65 | 0.055 | 0.065 |
| G | 2.54 BSC | | 0.100 BSC | |
| H | 0.51 | 1.27 | 0.020 | 0.050 |
| J | 0.20 | 0.30 | 0.008 | 0.012 |
| K | 3.18 | 4.06 | 0.125 | 0.160 |
| L | 7.62 BSC | | 0.300 BSC | |
| M | 0° | 15° | 0° | 15° |
| N | 0.25 | 1.02 | 0.010 | 0.040 |

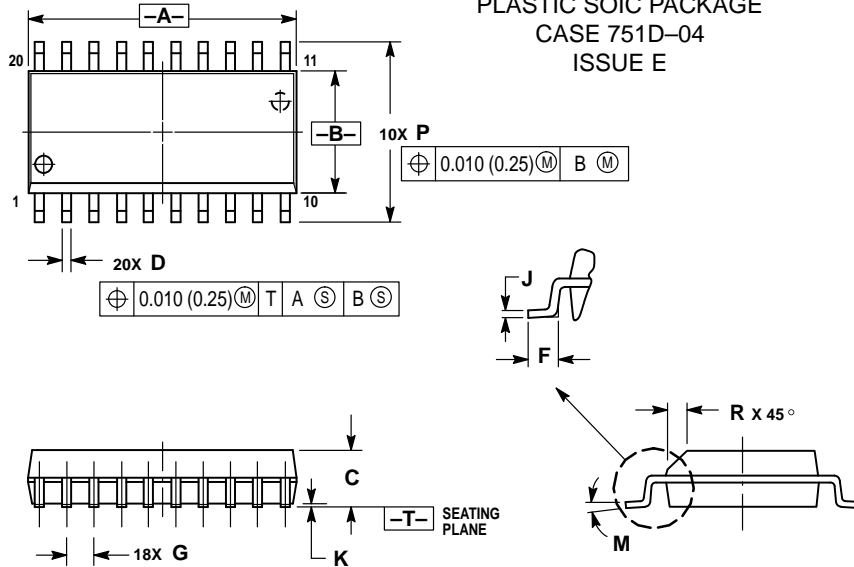
N SUFFIX
PLASTIC PACKAGE
CASE 738-03
ISSUE E



- NOTES:
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 - CONTROLLING DIMENSION: INCH.
 - DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 - DIMENSION B DOES NOT INCLUDE MOLD FLASH.

| DIM | INCHES | | MILLIMETERS | |
|-----|-----------|-------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 1.010 | 1.070 | 25.66 | 27.17 |
| B | 0.240 | 0.260 | 6.10 | 6.60 |
| C | 0.150 | 0.180 | 3.81 | 4.57 |
| D | 0.015 | 0.022 | 0.39 | 0.55 |
| E | 0.050 BSC | | 1.27 BSC | |
| F | 0.050 | 0.070 | 1.27 | 1.77 |
| G | 0.100 BSC | | 2.54 BSC | |
| J | 0.008 | 0.015 | 0.21 | 0.38 |
| K | 0.110 | 0.140 | 2.80 | 3.55 |
| L | 0.300 BSC | | 7.62 BSC | |
| M | 0° | 15° | 0° | 15° |
| N | 0.020 | 0.040 | 0.51 | 1.01 |

DW SUFFIX
PLASTIC SOIC PACKAGE
CASE 751D-04
ISSUE E

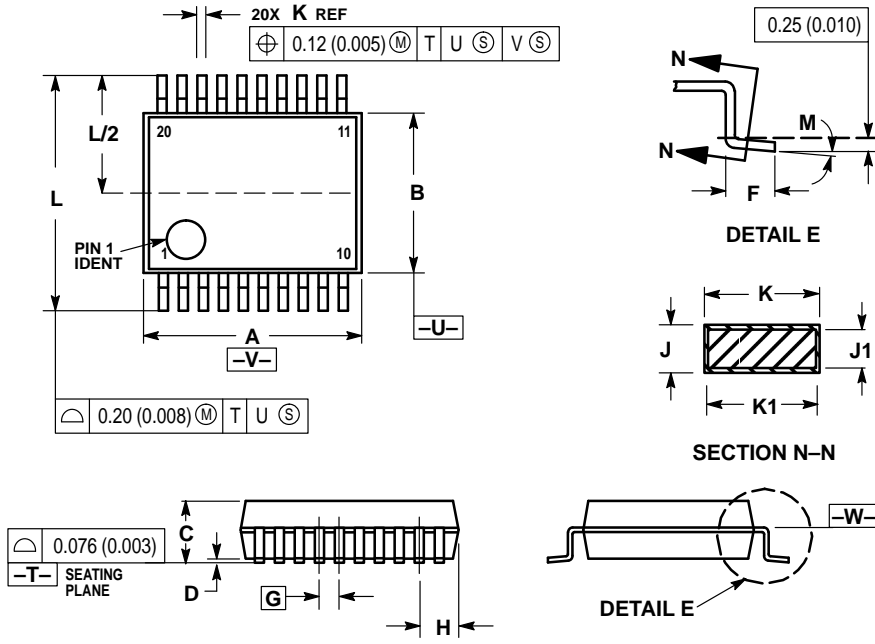


- NOTES:
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 - CONTROLLING DIMENSION: MILLIMETER.
 - DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 - MAXIMUM MOLD PROTRUSION 0.150 (0.006) PER SIDE.
 - DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|-------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 12.65 | 12.95 | 0.499 | 0.510 |
| B | 7.40 | 7.60 | 0.292 | 0.299 |
| C | 2.35 | 2.65 | 0.093 | 0.104 |
| D | 0.35 | 0.49 | 0.014 | 0.019 |
| F | 0.50 | 0.90 | 0.020 | 0.035 |
| G | 1.27 BSC | | 0.050 BSC | |
| J | 0.25 | 0.32 | 0.010 | 0.012 |
| K | 0.10 | 0.25 | 0.004 | 0.009 |
| M | 0° | 7° | 0° | 7° |
| P | 10.05 | 10.55 | 0.395 | 0.415 |
| R | 0.25 | 0.75 | 0.010 | 0.029 |

OUTLINE DIMENSIONS

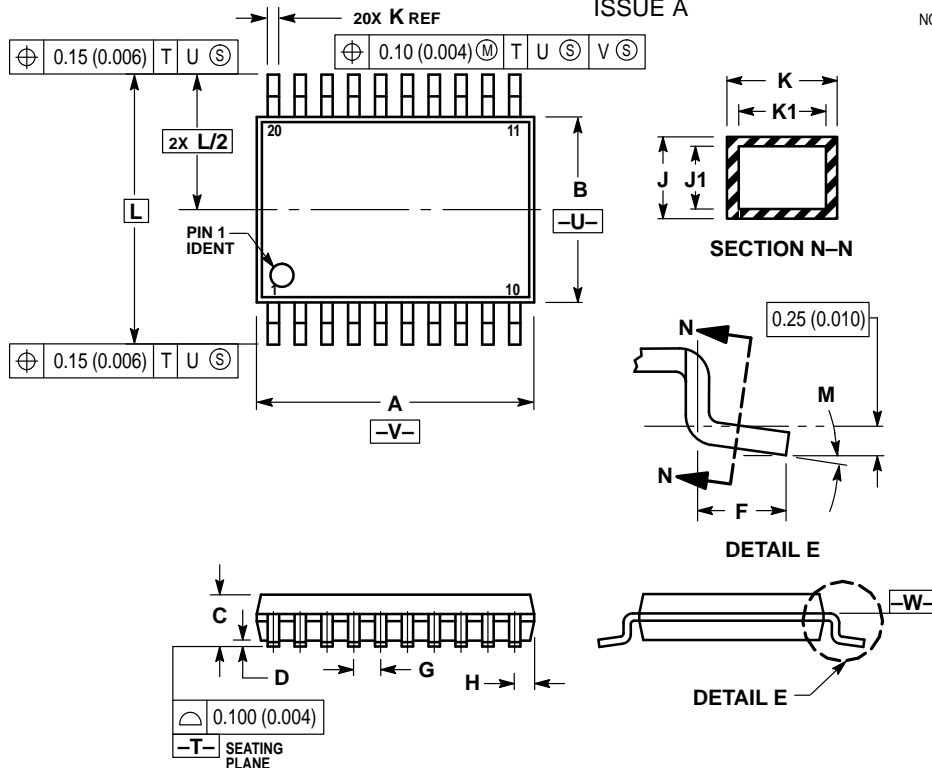
SD SUFFIX
PLASTIC SSOP PACKAGE
CASE 940C-03
ISSUE B



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION/INTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF K DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR INTRUSION SHALL NOT REDUCE DIMENSION K BY MORE THAN 0.07 (0.002) AT LEAST MATERIAL CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.


| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 7.07 | 7.33 | 0.278 | 0.288 |
| B | 5.20 | 5.38 | 0.205 | 0.212 |
| C | 1.73 | 1.99 | 0.068 | 0.078 |
| D | 0.05 | 0.21 | 0.002 | 0.008 |
| F | 0.63 | 0.95 | 0.024 | 0.037 |
| G | 0.65 BSC | | 0.026 BSC | |
| H | 0.59 | 0.75 | 0.023 | 0.030 |
| J | 0.09 | 0.20 | 0.003 | 0.008 |
| J1 | 0.09 | 0.16 | 0.003 | 0.006 |
| K | 0.25 | 0.38 | 0.010 | 0.015 |
| K1 | 0.25 | 0.33 | 0.010 | 0.013 |
| L | 7.65 | 7.90 | 0.301 | 0.311 |
| M | 0° | 8° | 0° | 8° |

DT SUFFIX
PLASTIC TSSOP PACKAGE
CASE 948E-02
ISSUE A



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 6.40 | 6.60 | 0.252 | 0.260 |
| B | 4.30 | 4.50 | 0.169 | 0.177 |
| C | — | 1.20 | — | 0.047 |
| D | 0.05 | 0.15 | 0.002 | 0.006 |
| F | 0.50 | 0.75 | 0.020 | 0.030 |
| G | 0.65 BSC | | 0.026 BSC | |
| H | 0.27 | 0.37 | 0.011 | 0.015 |
| J | 0.09 | 0.20 | 0.004 | 0.008 |
| J1 | 0.09 | 0.16 | 0.004 | 0.006 |
| K | 0.19 | 0.30 | 0.007 | 0.012 |
| K1 | 0.19 | 0.25 | 0.007 | 0.010 |
| L | 6.40 BSC | | 0.252 BSC | |
| M | 0° | 8° | 0° | 8° |

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JAPAN: Nippon Motorola Ltd.; Tatsumi-SPD-JLDC, 6F Seibu-Butsuryu-Center,
3-14-2 Tatsumi Koto-Ku, Tokyo 135, Japan. 03-81-3521-8315

ASIA/PACIFIC: Motorola Semiconductors H.K. Ltd.; 8B Tai Ping Industrial Park,
51 Ting Kok Road, Tai Po, N.T., Hong Kong. 852-26629298

